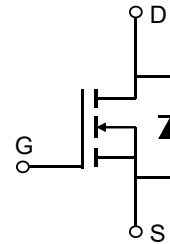


Description

Features

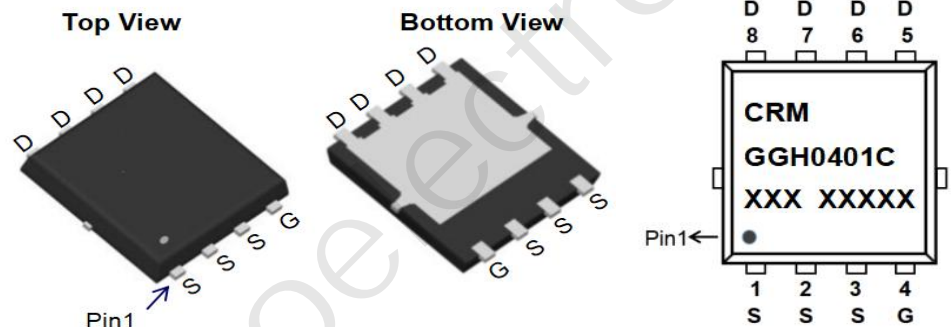
- 40V, 285A
 $R_{DS(ON)}$ Typ = 0.7mΩ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_d s TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH0401C	CRMGGH0401C	PDFN5x6-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	40	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	285
		$T_C = 100^\circ C$	171
I_{DM}	Pulsed Drain Current ⁽¹⁾	1140	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	841	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	125
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 40V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.3	2.8	3.4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	0.7	0.9	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 20V, f = 1MHz	-	5344	-	pF
C _{oss}	Output Capacitance		-	2363	-	pF
C _{rss}	Reverse Transfer Capacitance		-	200	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 20V, I _D = 30A	-	75	-	nC
Q _{gs}	Gate Source Charge		-	19	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	17.5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 20V I _D = 30A, R _{GEN} = 1.6Ω	-	8.5	-	ns
t _r	Turn-On Rise Time		-	15	-	ns
t _{d(off)}	Turn-Off DelayTime		-	52	-	ns
t _f	Turn-Off Fall Time		-	12	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	285	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	1140	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F = 30A, di/dt = 100A/us	-	22	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	40	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=20V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=58A
 3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Test Circuit

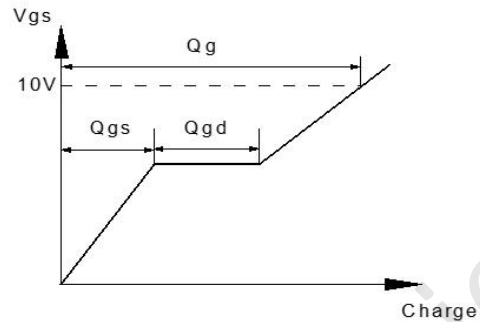
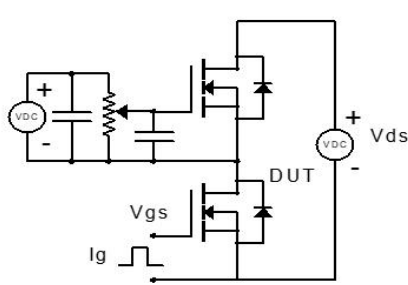


Figure 1: Gate Charge Test Circuit & Waveform

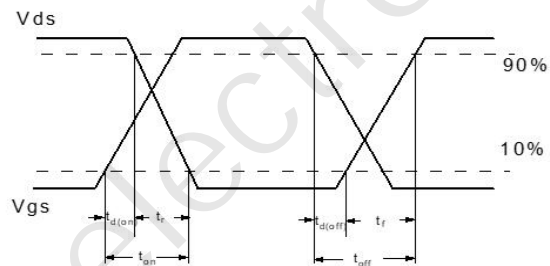
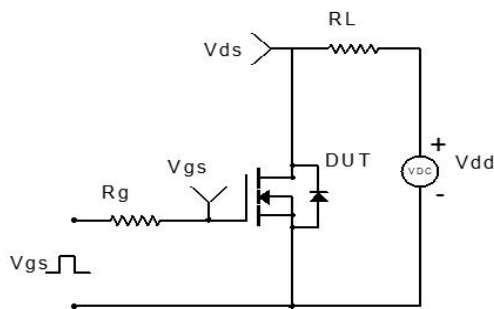


Figure 2: Resistive Switching Test Circuit & Waveform

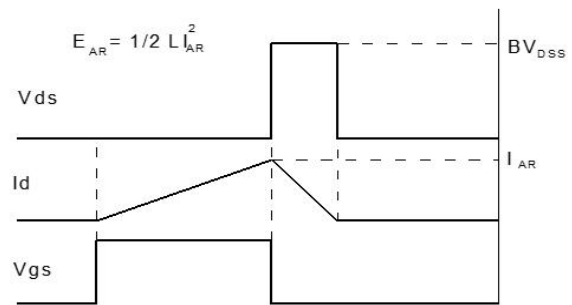
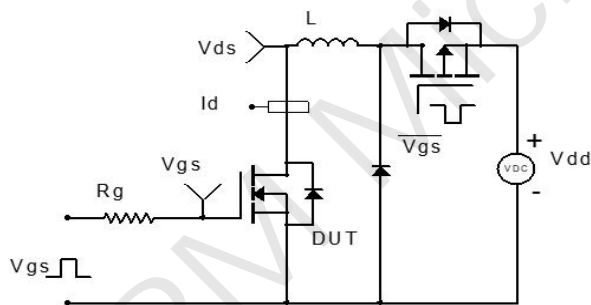


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

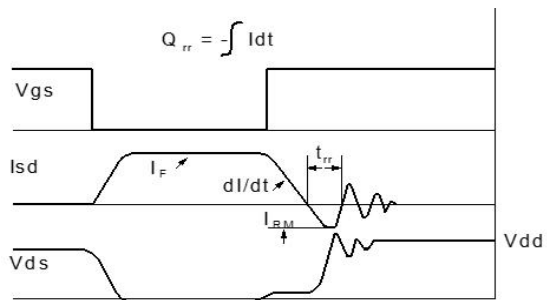
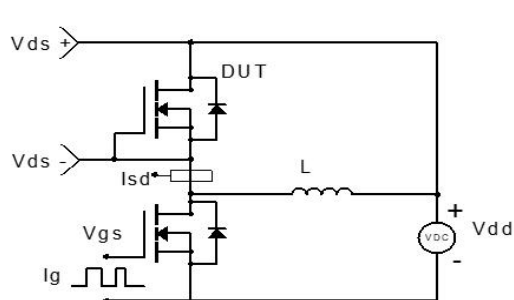
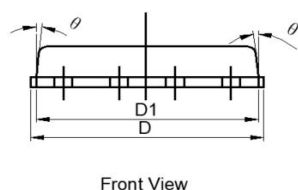
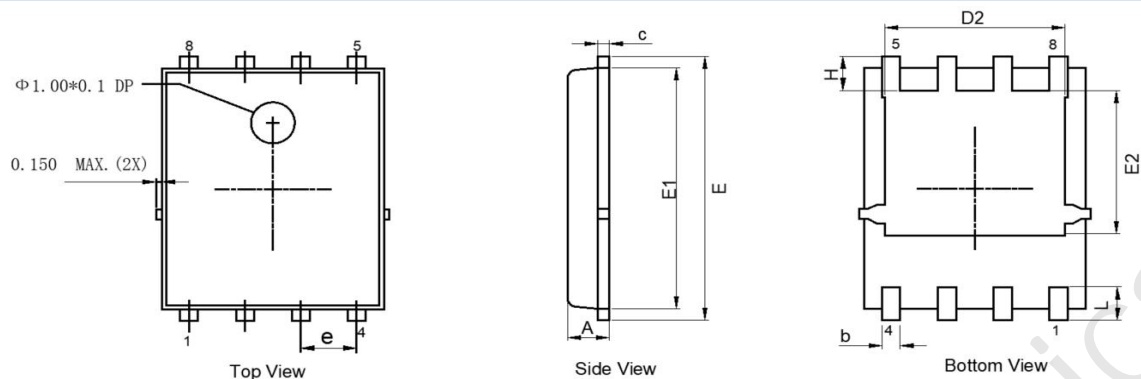


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)




DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	0.31	0.41	0.51
c	0.21	0.25	0.34
D	5.05	5.20	5.40
D1	4.95	5.05	5.15
D2	4.00	4.10	4.20
E	6.30	6.40	6.50
E1	5.75	5.85	5.95
E2	3.43	3.53	3.63
e	1.27BSC		
H	0.73	0.83	0.93
L	0.61	0.71	0.81
θ	0°	—	12°

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